

ELECTRONIC DEVICES AND ITS PRODUCTION METHODS

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ABSTRACT OF THE DISCLOSURE

10       An electronic device having mounted thereon an MEMS  
element or other functional elements, in which a device  
body and lid define an element-carrying space, the  
15       element-carrying space is sealed air-tight by an  
ultrasonic bonded part bonding the device body and the  
lid, and the element-carrying space having arranged  
inside it a system element secured to the device body  
and/or the lid by flip-chip connection.